

1. General description

W3MS80N010TL is a low voltage N-channel MOSFET in TOLL package, which utilizes the split gate technology to provide superior FOM $R_{DS(on)} * Q_g$ among silicon based MOSFETs. It is particularly suitable for applications require extreme high efficiency and power density.



2. Features and benefits

- High-speed switching
- Excellent gate charge x $R_{DS(on)}$ product (FOM)
- 100% avalanche tested

3. Applications

- Battery Management
- Load Switch
- Motor Drivers

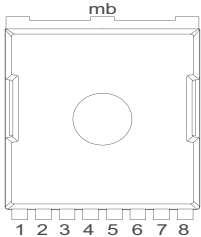
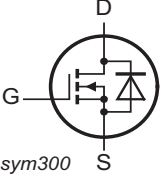
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V_{DS}	drain-source voltage			80			V
V_{GS}	gate-source voltage	static		±20			V
I_D	continuous drain current	$T_C = 25\text{ °C}$	[1]	400			A
P_{tot}	power dissipation	$T_C = 25\text{ °C}$		312			W
T_j	junction temperature			-55 to 150			°C
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}, I_D = 50\text{ A}$		-	0.85	1.0	mΩ
Dynamic characteristics							
$Q_{G(tot)}$	total gate charge	$I_D = 20\text{ A}; V_{DS} = 40\text{ V}; V_{GS} = 10\text{ V}$		-	181	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2-8	S	source		
mb	D	mounting base; connected to drain		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
W3MS80N010TL	TOLL	W3MS80N010TLJ	Reel	1800	TOLLO	11-Feb-2026

7. Marking

Table 4. Marking codes

Type number	Marking codes
W3MS80N010TL	W3MS 80N010TL

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{DS}	drain-source voltage			80	V
V_{GS}	gate-source voltage	static		± 20	V
I_D	continuous drain current	$T_C = 25\text{ }^\circ\text{C}$	[1]	400	A
		$T_C = 100\text{ }^\circ\text{C}$	[1]	250	A
I_{DM}	pulsed drain current	$T_C = 25\text{ }^\circ\text{C}$		1300	A
P_{tot}	power dissipation	$T_C = 25\text{ }^\circ\text{C}$		312	W
E_{AS}	single pulse drain-to-source avalanche	$I_{AS} = 58\text{ A}$; $R_{GS} = 25\text{ }\Omega$; $V_{DD} = 40\text{ V}$; $T_J = 25\text{ }^\circ\text{C}$		841	mJ
I_{AS}	avalanche current, single pulse			58	A
T_{stg}	storage temperature			-55 to 150	$^\circ\text{C}$
T_J	junction temperature			-55 to 150	$^\circ\text{C}$

Notes: [1] Calculated continuous current based on maximum allowable junction temperature.
Package current limitation is 240A.

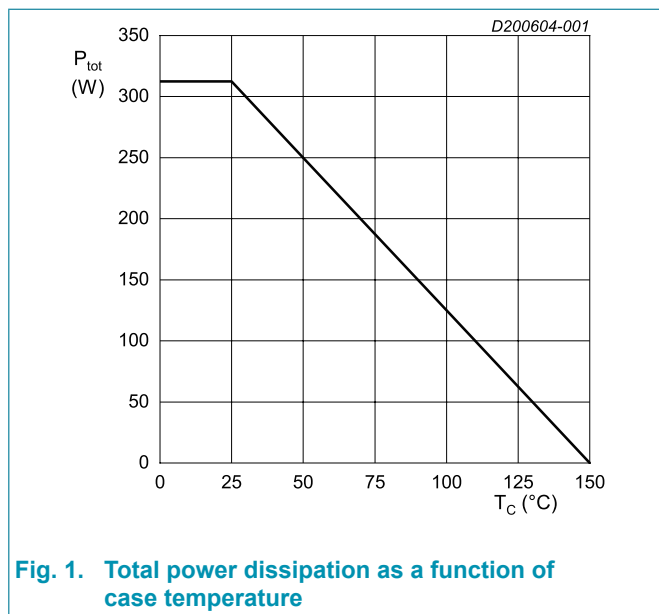


Fig. 1. Total power dissipation as a function of case temperature

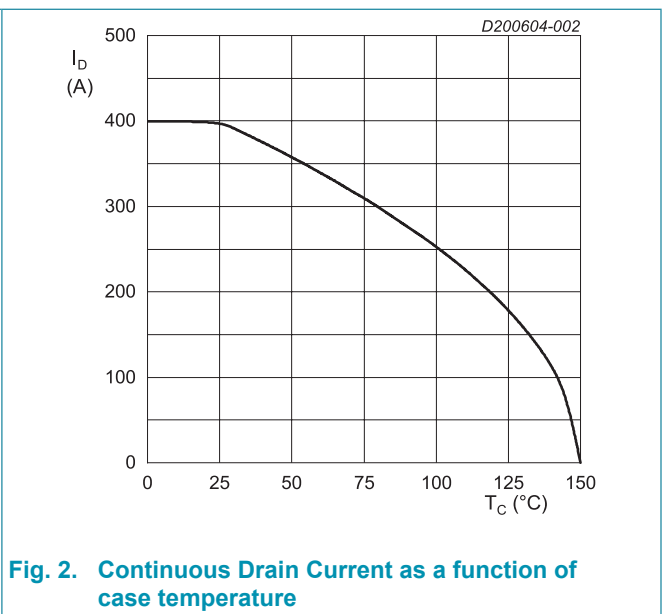


Fig. 2. Continuous Drain Current as a function of case temperature

9. Thermal & Mechanical characteristics

Table 6. Thermal & Mechanical characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-c)}$	thermal resistance from junction to case			-	0.28	0.4	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		-	45	-	K/W

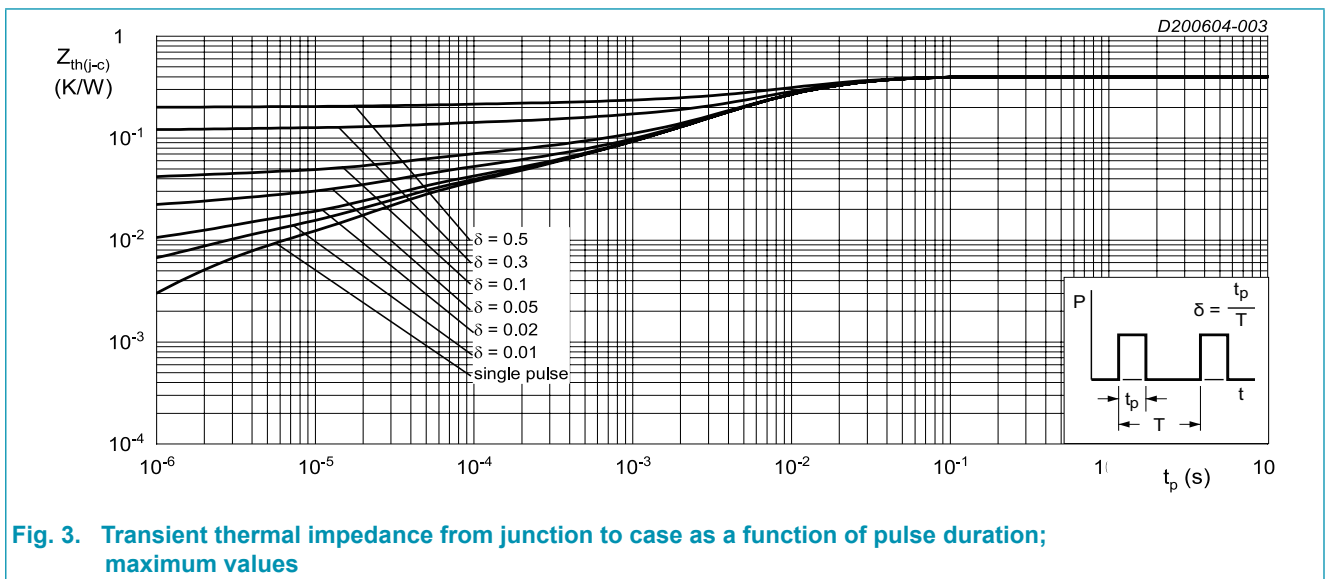


Fig. 3. Transient thermal impedance from junction to case as a function of pulse duration; maximum values

10. Characteristics

Table 7. Characteristics
 $T_j = 25\text{ °C}$ unless otherwise noted

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250\ \mu\text{A}; V_{GS} = 0\ \text{V}$		80	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 250\ \mu\text{A}; V_{DS} = V_{GS}$		2.0	2.8	4.0	V
I_{DSS}	drain leakage current	$V_{DS} = 100\ \text{V}; V_{GS} = 0\ \text{V}$		-	-	1	μA
		$V_{DS} = 100\ \text{V}; V_{GS} = 0\ \text{V}; T_j = 125\text{ °C}$		-	-	100	μA
I_{GSS}	gate leakage current	$V_{GS} = \pm 20\ \text{V}; V_{DS} = 0\ \text{V}$		-	-	± 100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\ \text{V}; I_D = 50\ \text{A}$		-	0.85	1.0	m Ω
R_G	gate resistance	$f = 1\ \text{MHz}$		-	1.2	-	Ω
g_{fs}	transconductance	$V_{DS} = 5\ \text{V}; I_D = 15\ \text{A}; T_j = 25\text{ °C}$		-	173	-	S
Dynamic characteristics							
$Q_{G(tot)}$	total gate charge	$I_D = 20\ \text{A}; V_{DS} = 40\ \text{V}; V_{GS} = 10\ \text{V}$		-	181	-	nC
Q_{GS}	gate-source charge			-	55	-	nC
Q_{GD}	gate-drain charge			-	25	-	nC
C_{iss}	input capacitance	$V_{DS} = 40\ \text{V}; V_{GS} = 0\ \text{V}; f = 250\ \text{KHz}$		-	13747	-	pF
C_{oss}	output capacitance			-	1828	-	pF
C_{rss}	reverse transfer capacitance			-	45	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 40\ \text{V}; V_{GS} = 10\ \text{V}; R_G = 1\ \Omega;$ $I_D = 20\ \text{A}$		-	43	-	ns
t_r	rise time			-	72	-	ns
$t_{d(off)}$	turn-off delay time			-	165	-	ns
t_f	fall time			-	76	-	ns
Source-drain diode							
V_{SD}	source-drain voltage	$V_{GS} = 0\ \text{V}; I_S = 20\ \text{A}$		-	0.78	-	V
I_S	body-diode continuous current	$T_C = 25\text{ °C}$		-	-	240	A
t_{rr}	reverse recovery time	$V_R = 50\ \text{V}; I_F = 20\ \text{A}; dI_F/dt = 100\ \text{A}/\mu\text{s}$		-	99	-	ns
Q_{rr}	reverse recovered charge			-	342	-	nC

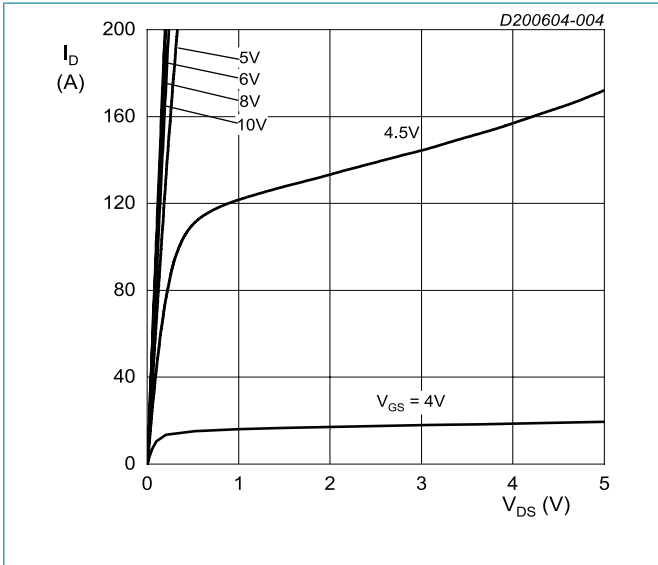
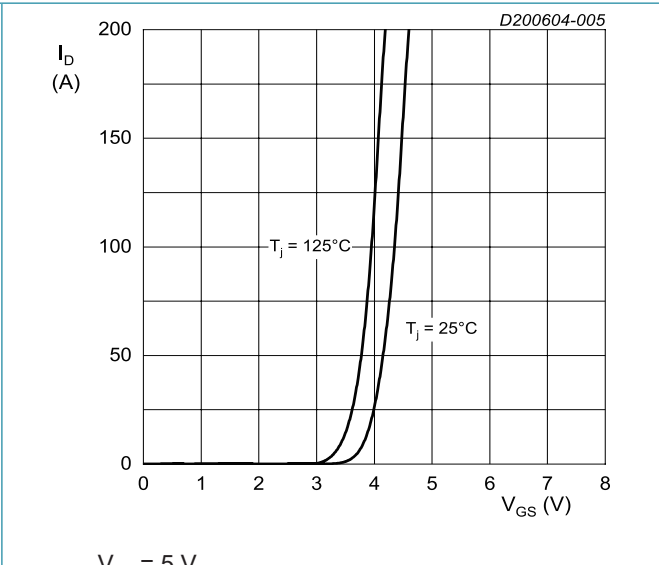


Fig. 4. Drain current as a function of drain-source voltage; typical values



$V_{DS} = 5V$
Fig. 5. Drain current as a function of gate-source voltage; typical values

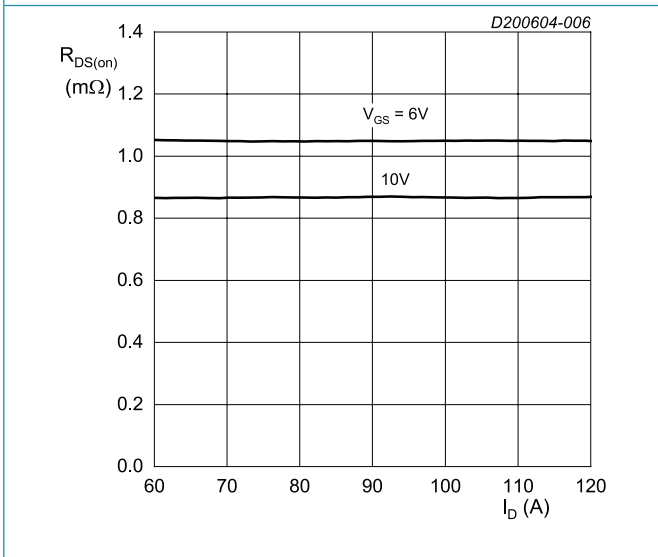
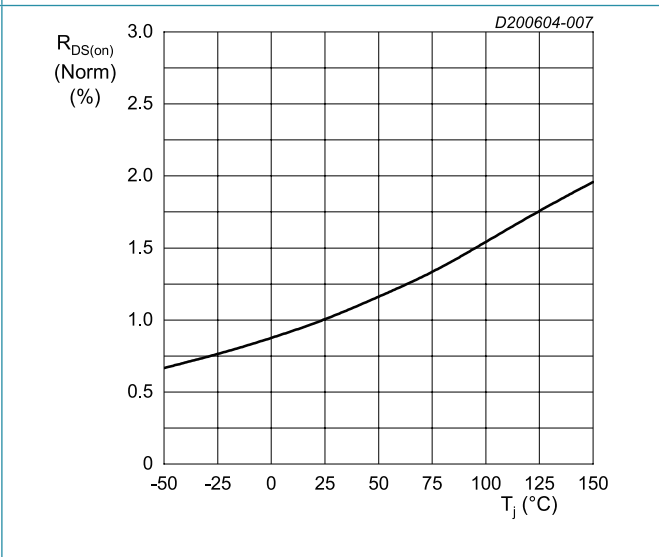
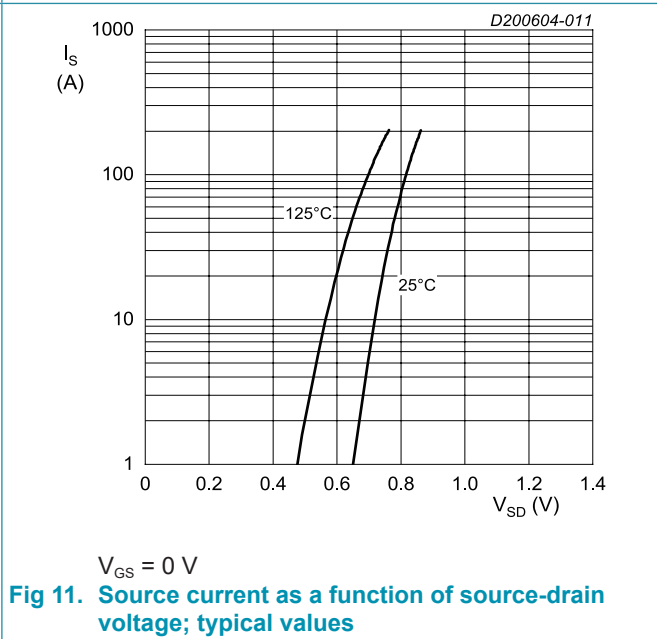
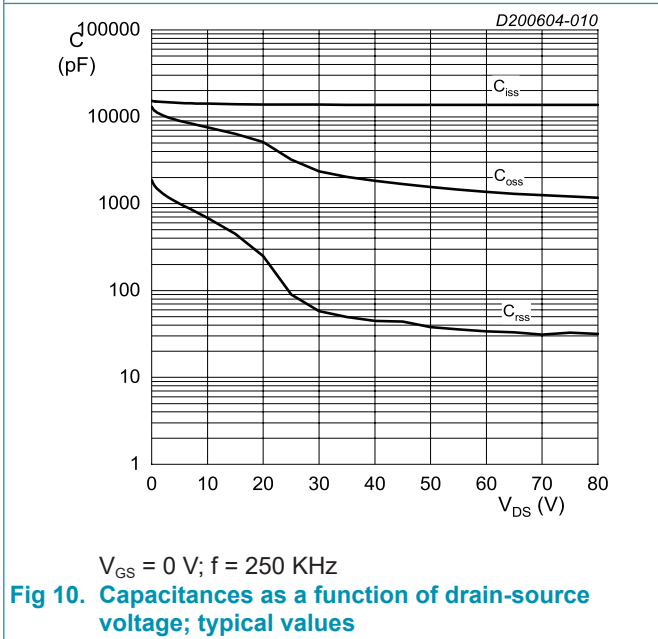
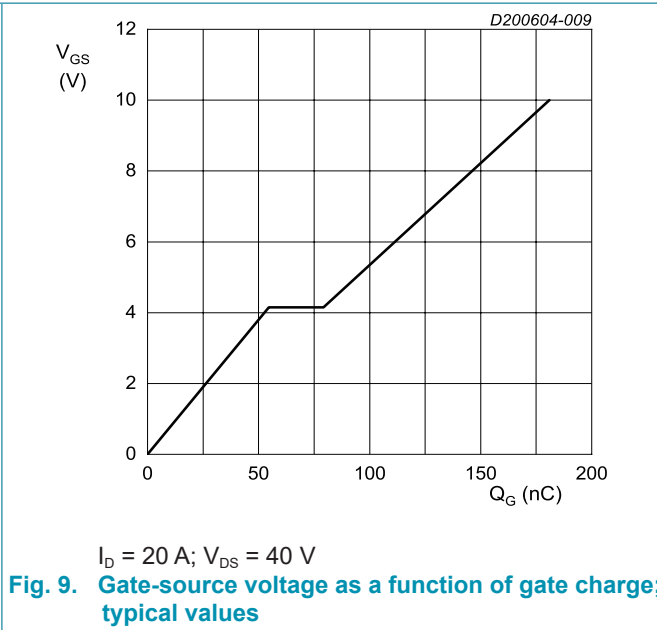
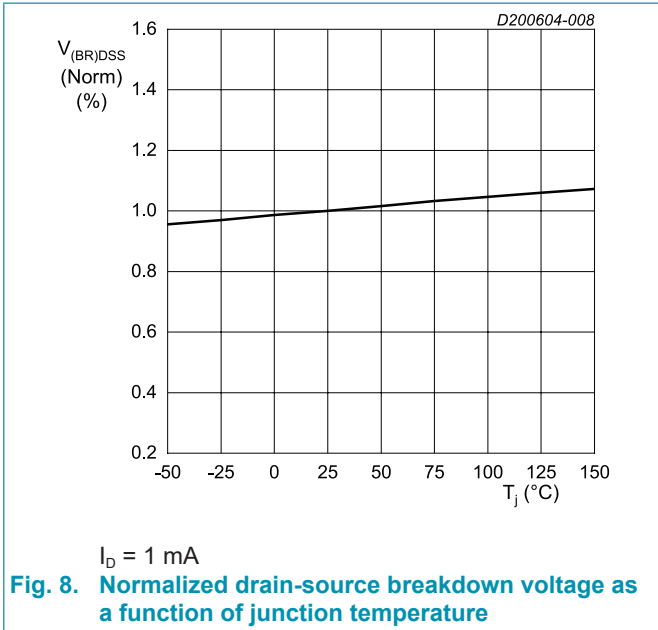


Fig. 6. Drain-source on-state resistance as a function of drain current; typical values



$V_{GS} = 10V$; $I_D = 50A$
Fig. 7. Normalized drain-source on-state resistance as a function of junction temperature



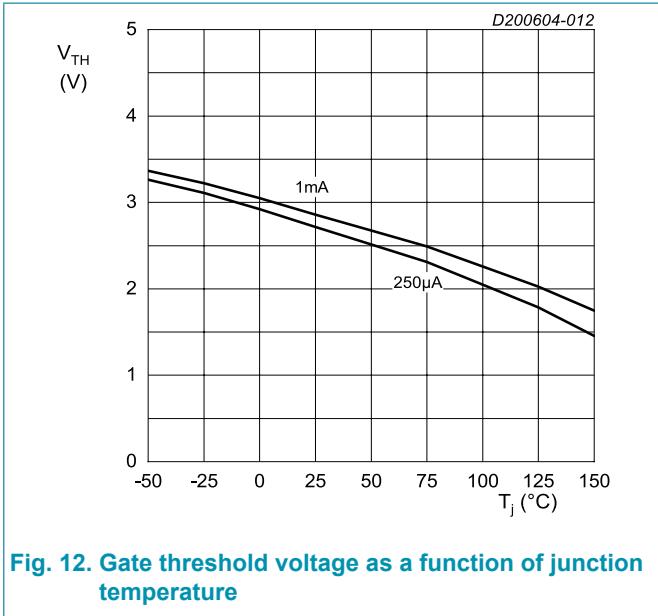


Fig. 12. Gate threshold voltage as a function of junction temperature

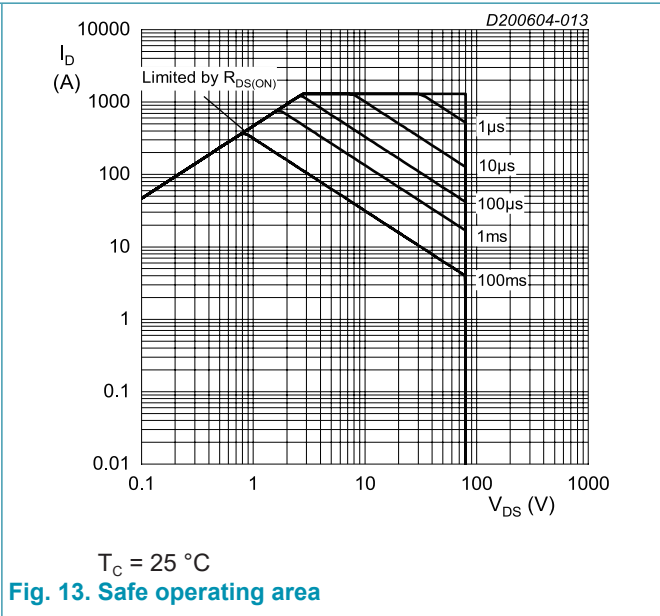
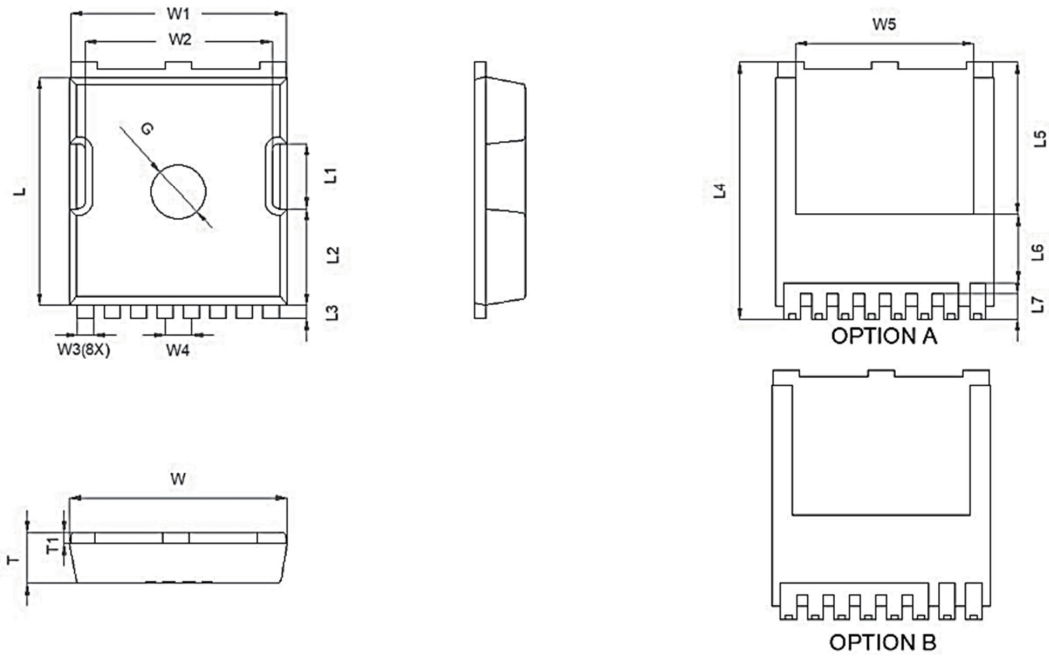


Fig. 13. Safe operating area

11. Package outline (option A)



Symbol	Dimensions		Symbol	Dimensions		Symbol	Dimensions	
	Min	Max		Min	Max		Min	Max
W	9.80	10.20	L1	1.00	1.4	T1	1.20	1.40
W1	(5.08)		L2	1.20	1.60	T2	2.20	2.60
W2	0.70	0.95	L3	15.00	15.60	T3	0.45	0.65
W3	1.17	1.62	L4	2.20	2.80	T4	0	0.25
W4	(8.0)		L5	(8.2)		θ	0°	8°
L	9.00	9.40	T	4.30	4.70			

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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